Package Outline Drawing
W4x5.20N
20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch) (With BSC)
Rev 0, 2/15

NOTES:
   △ Dimension is measured at the maximum bump diameter parallel to primary datum □.
   △ Primary datum □ and seating plane are defined by the spherical crowns of the bump.
   △ Bump position designation per JESD 95-1, SPP-010.
2. All dimensions are in millimeters.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.